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| --- |
| **PLEASE PROVIDE THE FOLLOWING INFORMATION:** |
| ASSEMBLY #: |       | ASSEMBLY NAME: |       |
| ASSY REV: |       | PCB REV: |       |
| CONTACT NAME: |       | PHONE #: |       |
| ACCOUNTS PAYABLE NAME: |       | ACCOUNTS PAYABLE EMAIL: |       |
|  |
| EXPECTED COMPLETION DATE OR TURN TIME (TURN TIME IS AFTER ALL MATERIALS ARE IN HOUSE): |
| DUE DATE: | CHOOSE DATE | TURN TIME: |       |
| QTY(S) REQUESTED: |       |
| IF MULTIPLE RELEASES, PLEASE SPECIFY DATES AND QUANTITIES NEEDED: |       |
| FORECAST: |  |
| ***DIE PLACEMENT SECTION*** |
| DIE PLACEMENT REQUIRED? |  | DIE PLACEMENT DRAWING PROVIDED? |  |
| IF NO DRAWING IS PROVIDED, LIST DIE PLACEMENT DETAILS INCLUDING TOLERANCES ON THE LINE BELOW: |
|       |
| DIE ATTACH CHEMISTRY: |  |       |
| ***DIE DETAILS:*** | PAD SIZE: |       | PAD MATERIAL: |       |
| ***SUBSTRATE DETAILS:*** | PAD SIZE: |       | PAD MATERIAL: |       |
| *CST’S PREFERRED PCB PLATING MATERIAL IS ENEPIG (30µ SOFT GOLD IS MINIMUM FOR WIRE BONDING)* |
| MAX Z CLEARANCE FOR DIE: |       | MAX Z CLEARANCE FOR SUBSTRATE: |       |
| SPEC SHEET FOR DIE PROVIDED? |  |
| ***WIRE BONDING SECTION*** |
| BOND TYPE: |  | BOND WIRE MATERIAL: |  |
| BOND WIRE THICKNESS: |  | NUMBER OF BONDS: |       |
| BONDING DRAWING: |  |
| BOND LENGTH(S):(DISTANCES FROM DIE PAD TO SUBSTRATE PAD) |       |
| AMPS PER BOND: |       | BONDING FIXTURE NEEDED? |  |
| *NOTE: FOR WIRE BONDING ALL COMPONENTS NEED TO BE ABLE TO WITHSTAND 130ºC* |
| SHEAR/PULL TESTING REQUIRED? |  | TESTING REQUIRED? |  |
| TEST EQUIPMENT NEEDED? |  | TEST PROCEDURE: |  |
| PROTECTIVE PACKAGING FOR WIRE BONDS? |       |
| ***ENCAPSULATION SECTION*** |
| ENCAPSULATION METHOD(S): | [ ]  GLOB TOP | [ ]  DAM & FILL | [ ]  POTTING | [ ]  NO ENCAPSULATION |
| LIST ALL REQUIRED CHEMISTRIES: |       |
| IF PERFORMING GLOB TOP→ | REQUIREMENTS: | [ ]  THERMAL | [ ]  WATER-PROOF | [ ]  COLORED |
| [ ]  OTHER: |       |
| MAX HEIGHT: |       | DIMENSIONS: |       |
| **↓NOTES/COMMENTS↓** |
|       |
| ↑CLICK TO INSERT PICTURE↑ | ↑CLICK TO INSERT PICTURE↑ |